捷多邦,专业PCB打样工**TMS320003担TM**S320LC31 DIGITAL SIGNAL PROCESSORS

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- High-Performance Floating-Point Digital Signal Processor (DSP):
 - TMS320C31-80 (5 V)
 25-ns Instruction Cycle Time
 440 MOPS, 80 MFLOPS, 40 MIPS
 - TMS320C31-60 (5 V)
 33-ns Instruction Cycle Time
 330 MOPS, 60 MFLOPS, 30 MIPS
 - TMS320C31-50 (5 V)
 40-ns Instruction Cycle Time
 275 MOPS, 50 MFLOPS, 25 MIPS
 - TMS320C31-40 (5 V)
 50-ns Instruction Cycle Time
 220 MOPS, 40 MFLOPS, 20 MIPS
 - TMS320LC31-40 (3.3 V)
 50-ns Instruction Cycle Time
 220 MOPS, 40 MFLOPS, 20 MIPS
 - TMS320LC31-33 (3.3 V)60-ns Instruction Cycle Time183.7 MOPS, 33.3 MFLOPS, 16.7 MIPS
- 32-Bit High-Performance CPU
- 16-/32-Bit Integer and 32-/40-Bit Floating-Point Operations
- 32-Bit Instruction Word, 24-Bit Addresses
- Two 1K × 32-Bit Single-Cycle Dual-Access On-Chip RAM Blocks
- Boot-Program Loader

- On-Chip Memory-Mapped Peripherals:
 - One Serial Port
 - Two 32-Bit Timers
 - One-Channel Direct Memory Access (DMA) Coprocessor for Concurrent I/O and CPU Operation
- Fabricated Using 0.6 μm Enhanced
 Performance Implanted CMOS (EPIC™)
 Technology by Texas Instruments (TI™)
- 132-Pin Plastic Quad Flat Package (PQ Suffix)
- Eight Extended-Precision Registers
- Two Address Generators With Eight Auxiliary Registers and Two Auxiliary Register Arithmetic Units (ARAUs)
- Two Low-Power Modes
- Two- and Three-Operand Instructions
- Parallel Arithmetic/Logic Unit (ALU) and Multiplier Execution in a Single Cycle
- Block-Repeat Capability
- Zero-Overhead Loops With Single-Cycle Branches
- Conditional Calls and Returns
- Interlocked Instructions for Multiprocessing Support
- Bus-Control Registers Configure
 Strobe-Control Wait-State Generation

description

The TMS320C31 and TMS320LC31 DSPs are 32-bit, floating-point processors manufactured in 0.6 μm triple-level-metal CMOS technology. The TMS320C31 and TMS320LC31 are part of the TMS320C3x generation of DSPs from Texas Instruments.

The TMS320C3x's internal busing and special digital-signal-processing instruction set have the speed and flexibility to execute up to 80 million floating-point operations per second (MFLOPS). The TMS320C3x optimizes speed by implementing functions in hardware that other processors implement through software or microcode. This hardware-intensive approach provides performance previously unavailable on a single chip.

The TMS320C3x can perform parallel multiply and ALU operations on integer or floating-point data in a single cycle. Each processor also possesses a general-purpose register file, a program cache, dedicated ARAUs, internal dual-access memories, one DMA channel supporting concurrent I/O, and a short machine-cycle time. High performance and ease of use are results of these features.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.





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description (continued)

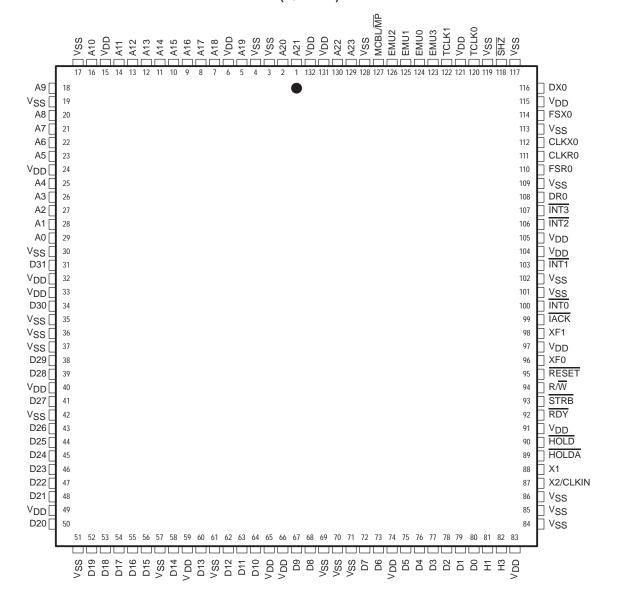
General-purpose applications are greatly enhanced by the large address space, multiprocessor interface, internally and externally generated wait states, one external interface port, two timers, one serial port, and multiple-interrupt structure. The TMS320C3x supports a wide variety of system applications from host processor to dedicated coprocessor.

High-level-language support is easily implemented through a register-based architecture, large address space, powerful addressing modes, flexible instruction set, and well-supported floating-point arithmetic.

TMS320C31 and TMS320LC31 pinout (top view)

The TMS320C31 and TMS320LC31 devices are packaged in 132-pin plastic quad flatpacks (PQ Suffix).

PQ PACKAGE (TOP VIEW)





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TMS320C31 and TMS320LC31 Terminal Assignments (Alphabetical)†

TERMI	NAL	TERM	INAL	TERMI	NAL	TERMI	NAL	TERMI	NAL
NAME	NO.	NAME	NO.	NAME	NO.	NAME	NO.	NAME	NO.
A0	29	D4	76	EMU0	124	V_{DD}	40	V _{SS}	84
A1	28	D5	75	EMU1	125	V_{DD}	49	VSS	85
A2	27	D6	73	EMU2	126	V_{DD}	59	VSS	86
A3	26	D7	72	EMU3	123	V_{DD}	65	VSS	101
A4	25	D8	68	FSR0	110	V_{DD}	66	VSS	102
A5	23	D9	67	FSX0	114	V_{DD}	74	VSS	109
A6	22	D10	64	H1	81	V_{DD}	83	VSS	113
A7	21	D11	63	H3	82	V_{DD}	91	VSS	117
A8	20	D12	62	HOLD	90	V_{DD}	97	VSS	119
A9	18	D13	60	HOLDA	89	V_{DD}	104	VSS	128
A10	16	D14	58	IACK	99	V_{DD}	105	X1	88
A11	14	D15	56	ĪNT0	100	V_{DD}	115	X2/CLKIN	87
A12	13	D16	55	ĪNT1	103	V_{DD}	121	XF0	96
A13	12	D17	54	ĪNT2	106	V_{DD}	131	XF1	98
A14	11	D18	53	ĪNT3	107	V_{DD}	132		
A15	10	D19	52	MCBL/MP	127	VSS	3		
A16	9	D20	50	RDY	92	VSS	4		
A17	8	D21	48	RESET	95	VSS	17		
A18	7	D22	47	R/W	94	VSS	19		
A19	5	D23	46	SHZ	118	VSS	30		
A20	2	D24	45	STRB	93	V _{SS}	35		
A21	1	D25	44	TCLK0	120	V _{SS}	36		
A22	130	D26	43	TCLK1	122	VSS	37		
A23	129	D27	41			VSS	42		
CLKR0	111	D28	39			VSS	51		
CLKX0	112	D29	38	V_{DD}	6	VSS	57		
D0	80	D30	34	V_{DD}	15	VSS	61		
D1	79	D31	31	V_{DD}	24	VSS	69		
D2	78	DR0	108	V_{DD}	32	VSS	70		
D3	77	DX0	116	V_{DD}	33	VSS	71		

[†]V_{DD} and V_{SS} pins are on a common plane internal to the device.

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TMS320C31 and TMS320LC31 Terminal Assignments (Numerical) †

TER	MINAL	TER	RMINAL	TER	RMINAL	TER	MINAL	TEI	RMINAL
NO.	NAME	NO.	NAME	NO.	NAME	NO.	NAME	NO.	NAME
1	A21	31	D31	61	V_{SS}	91	V_{DD}	121	V_{DD}
2	A20	32	V_{DD}	62	D12	92	RDY	122	TCLK1
3	V_{SS}	33	V_{DD}	63	D11	93	STRB	123	EMU3
4	V_{SS}	34	D30	64	D10	94	R/\overline{W}	124	EMU0
5	A19	35	Vss	65	V_{DD}	95	RESET	125	EMU1
6	V_{DD}	36	VSS	66	V_{DD}	96	XF0	126	EMU2
7	A18	37	V_{SS}	67	D9	97	V_{DD}	127	MCBL/MP
8	A17	38	D29	68	D8	98	XF1	128	V_{SS}
9	A16	39	D28	69	V_{SS}	99	IACK	129	A23
10	A15	40	V_{DD}	70	VSS	100	INT0	130	A22
11	A14	41	D27	71	Vss	101	VSS	131	V _{DD}
12	A13	42	V_{SS}	72	D7	102	VSS	132	V_{DD}
13	A12	43	D26	73	D6	103	INT1		
14	A11	44	D25	74	V_{DD}	104	V_{DD}		
15	V_{DD}	45	D24	75	D5	105	V_{DD}		
16	A10	46	D23	76	D4	106	INT2		
17	V_{SS}	47	D22	77	D3	107	INT3		
18	A9	48	D21	78	D2	108	DR0		
19	V_{SS}	49	V_{DD}	79	D1	109	VSS		
20	A8	50	D20	80	D0	110	FSR0		
21	A7	51	V _{SS}	81	H1	111	CLKR0		
22	A6	52	D19	82	НЗ	112	CLKX0		
23	A5	53	D18	83	V_{DD}	113	VSS		
24	V_{DD}	54	D17	84	VSS	114	FSX0		
25	A4	55	D16	85	Vss	115	V_{DD}		
26	А3	56	D15	86	Vss	116	DX0		
27	A2	57	V_{SS}	87	X2/CLKIN	117	V_{SS}		
28	A1	58	D14	88	X1	118	SHZ		
29	A0	59	V_{DD}	89	HOLDA	119	V_{SS}		
30	VSS	60	D13	90	HOLD	120	TCLK0		

TVDD and VSS pins are on a common plane internal to the device.

TMS320C31 and TMS320LC31 Terminal Functions

TERMIN NAME	IAL QTY	TYPE [†]	DESCRIPTION		NDITIO WHEN AL IS Z	
			PRIMARY-BUS INTERFACE			
D31-D0	32	I/O/Z	32-bit data port	S	Н	R
A23-A0	24	O/Z	24-bit address port	S	Н	R
R/\overline{W}	1	O/Z	Read/write. R/\overline{W} is high when a read is performed and low when a write is performed over the parallel interface.	S	Н	R
STRB	1	O/Z	External-access strobe	S	Н	
RDY	1	I	Ready. RDY indicates that the external device is prepared for a transaction completion.			
HOLD	1	I	Hold. When HOLD is a logic low, any ongoing transaction is completed. A23–A0, D31–D0, STRB, and R/W are placed in the high-impedance state and all transactions over the primary-bus interface are held until HOLD becomes a logic high or until the NOHOLD bit of the primary-bus-control register is set.			
HOLDA	1	O/Z	Hold acknowledge. HOLDA is generated in response to a logic low on HOLD. HOLDA indicates that A23–A0, D31–D0, STRB, and R/W are in the high-impedance state and that all transactions over the bus are held. HOLDA is high in response to a logic high of HOLD or the NOHOLD bit of the primary-bus-control register is set.	S		
		-	CONTROL SIGNALS			
RESET	1	I	Reset. When RESET is a logic low, the device is in the reset condition. When RESET becomes a logic high, execution begins from the location specified by the reset vector.			
INT3-INT0	4	ı	External interrupts			
IACK	1	O/Z	Interrupt acknowledge. IACK is generated by the IACK instruction. IACK can be used to indicate the beginning or the end of an interrupt-service routine.	S		
MCBL/MP	1	ı	Microcomputer boot-loader/microprocessor mode-select			
SHZ	1	I	Shutdown high impedance. When active, SHZ shuts down the device and places all pins in the high-impedance state. SHZ is used for board-level testing to ensure that no dual-drive conditions occur. CAUTION: A low on SHZ corrupts the device memory and register contents. Reset the device with SHZ high to restore it to a known operating condition.			
XF1, XF0	2	I/O/Z	External flags. XF1 and XF0 are used as general-purpose I/Os or to support interlocked processor instruction.	S		R
			SERIAL PORT 0 SIGNALS			
CLKR0	1	I/O/Z	Serial port 0 receive clock. CLKR0 is the serial shift clock for the serial port 0 receiver.	S		R
CLKX0	1	I/O/Z	Serial port 0 transmit clock. CLKX0 is the serial shift clock for the serial port 0 transmitter.	S		R
DR0	1	I/O/Z	Data-receive. Serial port 0 receives serial data on DR0.	S		R
DX0	1	I/O/Z	Data-transmit output. Serial port 0 transmits serial data on DX0.	S		R
FSR0	1	I/O/Z	Frame-synchronization pulse for receive. The FSR0 pulse initiates the data-receive process using DR0.	S		R
FSX0	1	I/O/Z	Frame-synchronization pulse for transmit. The FSX0 pulse initiates the data-transmit process using DX0.	S		R
			TIMER SIGNALS			
TCLK0	1	I/O/Z	Timer clock 0. As an input, TCLK0 is used by timer 0 to count external pulses. As an output, TCLK0 outputs pulses generated by timer 0.	S		R
TCLK1	1	I/O/Z	Timer clock 1. As an input, TCLK0 is used by timer 1 to count external pulses. As an output, TCLK1 outputs pulses generated by timer 1.	S		R

[†] I = input, O = output, Z = high-impedance state ‡ S = \overline{SHZ} active, H = \overline{HOLD} active, R = \overline{RESET} active



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TMS320C31 and TMS320LC31 Terminal Functions (Continued)

TERMINA NAME	L QTY	TYPE†	DESCRIPTION	CONDITIONS WHEN SIGNAL IS Z TYPE‡
			SUPPLY AND OSCILLATOR SIGNALS	
H1	1	O/Z	External H1 clock. H1 has a period equal to twice CLKIN.	S
H3	1	O/Z	External H3 clock. H3 has a period equal to twice CLKIN.	S
V _{DD}	20	ı	5-V supply for 'C31 devices and 3.3-V supply for 'LC31 devices. All must be connected to a common supply plane.§	
VSS	25	I	Ground. All grounds must be connected to a common ground plane.	
X1	1	0	Output from the internal-crystal oscillator. If a crystal is not used, X1 should be left unconnected.	
X2/CLKIN	1	ı	Internal-oscillator input from a crystal or a clock	
		-	RESERVED¶	
EMU2-EMU0	3	I	Reserved for emulation. Use pullup resistors to $V_{\mbox{DD}}$	
EMU3	1	O/Z	Reserved for emulation	S

- NOTES: 1. A test mode for measuring leakage currents in the TMS320C31 is implemented. This test mode powers down the clock oscillator circuit resulting in currents below 10 µA. The test mode is entered by asserting SHZ low, which tri-states all output pins and then holds both H1 and H3 at logic high. The test mode is not intended for application use because it does not preserve the processor
 - 2. Since SHZ is a synchronized input and the clock is disabled, exiting the test mode occurs only when at least one of the H1/H3 pins is pulled low. Reset cannot be used to wake up in test mode since the SHZ pin is sampled and the clocks are not running.
 - 3. On power up, the processor can be in an indeterminate state. If the state is SHZ mode and H1 and H3 are both held logic high by pull-ups, then shutdown will occur. Normally, if H1 and H3 do not have pull-ups, the rise time lag due to capacitive loading on a tri-state pin is enough to ensure a clean start. However, a slowly rising supply and board leakages to V_{CC} may be enough to cause a bad start. Therefore, a pulldown resistor on either H1 or H3 is recommended for proper wakeup.

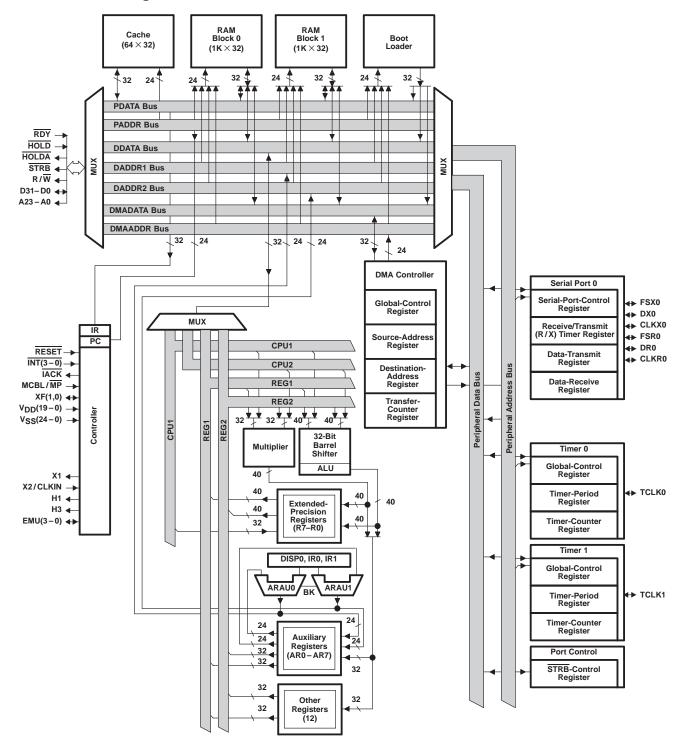


[†] I = input, O = output, Z = high-impedance state‡ S = $\overline{\text{SHZ}}$ active, H = $\overline{\text{HOLD}}$ active, R = $\overline{\text{RESET}}$ active

[§] Recommended decoupling capacitor value is 0.1 μF.

 $[\]P$ Follow the connections specified for the reserved pins. Use 18-k Ω – 22-k Ω pullup resistors for best results. All V_{DD} supply pins must be connected to a common supply plane, and all ground pins must be connected to a common ground plane.

functional block diagram



memory map

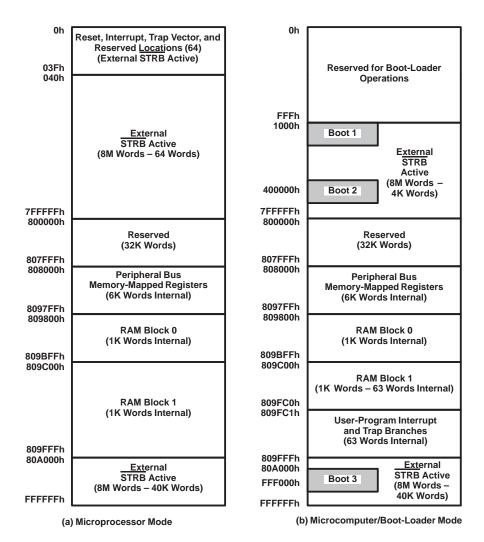


Figure 1. TMS320C31 Memory Maps

memory map (continued)

00h		2005041	
oon	Reset	809FC1h	INT0
01h	INT0	809FC2h	INT1
02h	INT1	809FC3h	INT2
03h	INT2	809FC4h	INT3
04h	INT3	809FC5h	
05h	XINT0	809FC5N	XINT0
06h	RINT0	809FC6h	RINT0
07h 08h	Reserved	809FC7h 809FC8h	Reserved
09h	TINT0	809FC9h	TINTO
0Ah	TINT1	809FCAh	TINT1
0Bh	DINT	809FCBh	DINT
0Ch 1Fh	Reserved	809FCCh 809FDFh	Reserved
20h	TRAP 0	809FE0h	TRAP 0
	•		•
	•		
3Bh	TRAP 27	809FFBh	TRAP 27
3Ch 3Fh	Reserved	809FFCh 809FFFh	Reserved
'	(a) Microprocessor Mode		Microcomputer/Boot-Loader Mode

Figure 2. Reset, Interrupt, and Trap Vector/Branches Memory-Map Locations

memory map (continued)

808000h	DMA Global Control
808004h	DMA Source Address
808006h	DMA Destination Address
808008h	DMA Transfer Counter
808020h	Timer 0 Global Control
808024h	Timer 0 Counter
808028h	Timer 0 Period Register
808030h	Timer 1 Global Control
808034h	Timer 1 Counter
808038h	Timer 1 Period Register
808040h	Serial Global Control
808042h	FSX/DX/CLKX Serial Port Control
808043h	FSR/DR/CLKR Serial Port Control
808044h	Serial R/X Timer Control
808045h	Serial R/X Timer Counter
808046h	Serial R/X Timer Period Register
808048h	Data-Transmit
80804Ch	Data-Receive
808064h	Primary-Bus Control

[†]Shading denotes reserved address locations

Figure 3. Peripheral Bus Memory-Mapped Registers[†]

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absolute maximum ratings over specified temperature range (unless otherwise noted)†

	'C31	'LC31
Supply voltage range, V _{DD} (see Note 1)	0.3 V to 7 V	0.3 V to 5 V
Input voltage range, V _I	0.3 V to 7 V	0.3 V to 5 V
Output voltage range, V _O	0.3 V to 7 V	–0.3 V to 5 V
Continuous power dissipation (worst case	e) (see Note 5) 2.6 W (for TMS320C31-80)	
Operating case temperature range, T _C	PQL (commercial) 0°C to 85°C	0°C to 85°C
	PQA (industrial)40°C to 125°C	
Storage temperature range, T _{stq}	– 55°C to 150°C	– 55°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 4. All voltage values are with respect to VSS.

recommended operating conditions (see Note 6)

			'C31			'LC31		UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
V_{DD}	Supply voltage (DV _{DD} , etc.)	4.75	5	5.25	3.13	3.3	3.47	V
VSS	Supply voltage (CV _{SS} , etc.)		0			0		V
VIH	High-level input voltage	2		V _{DD} + 0.3 [‡]	1.8		V _{DD} + 0.3 [‡]	V
V _{IL}	Low-level input voltage	- 0.3‡		0.8	- 0.3‡		0.6	V
ІОН	High-level output current			- 300			- 300	μΑ
loL	Low-level output current			2			2	mA
TC	Operating case temperature (commercial)	0		85	0		85	°C
	Operating case temperature (industrial)	- 40		125				°C
VTH	High-level input voltage for CLKIN	2.6		V _{DD} + 0.3 [‡]	2.5		$V_{DD} + 0.3^{\ddagger}$	V

[‡]These values are derived from characterization and not tested.

NOTE 6: All voltage values are with respect to VSS. All input and output voltage levels are TTL-compatible. CLKIN can be driven by a CMOS clock.



Actual operating power is less. This value was obtained under specially produced worst-case test conditions for the TMS320C31, which are not sustained during normal device operation. These conditions consist of continuous parallel writes of a checkerboard pattern to both primary and extension buses at the maximum rate possible. See normal (I_{CC}) current specification in the electrical characteristics table and also read *Calculation of TMS320C30 Power Dissipation Application Report* (literature number SPRA020).

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electrical characteristics over recommended ranges of supply voltage (unless otherwise noted) (see Note 3)[†]

	DADAMETED		TF.6	CT CONDITION	10		'C31			'LC31		LINUT
	PARAMETER		l les	ST CONDITION	15	MIN	TYP [‡]	MAX	MIN	TYP [‡]	MAX	UNIT
Vон	High-level output	voltage	V _{DD} = MIN, I	I _{OH} = MAX		2.4	3		2			V
VOL	Low-level output	voltage	$V_{DD} = MIN, I$	I _{OH} = MAX			0.3	0.6			0.4	V
IZ	High-impedance	current	$V_{DD} = MAX$			- 20		+ 20	- 20		+ 20	μΑ
II	Input current		$V_I = V_{SS}$ to V	DD		- 10		+ 10	- 10		+ 10	μΑ
Ι _{ΙΡ}	Input current (wit pullup)	h internal	Inputs with inte	ernal pullups§		- 600		20	- 600		10	μΑ
				f _X = 33 MHz	'LC31-33		150	325		120	250	
				f _X = 33 MHz	'C31-33 (ext. temp)		150	325				
ICC	Supply current¶#		$T_A = 25^{\circ}C$, $V_{DD} = MAX$	f _X = 40 MHz	'C31-40		160	390		150	300	mA
			V DD - WAX	f _X = 50 MHz	'C31-50		200	425				
				f _X = 60 MHz	'C31-60		225	475				
				f _X = 80 MHz	'C31-80		275	550				
I_{DD}	Supply current	_	Standby,	IDLE2 Clock	ks shut off		50			20		μΑ
Ci	Input	All inputs e	except CLKIN					15			15	pF
<u> </u>	capacitance	CLKIN						25			25	PF
Co	Output capacitan	ice						20			20	pF

[†] All input and output voltage levels are TTL compatible.

NOTE 6: All voltage values are with respect to V_{SS}. All input and output voltage levels are TTL-compatible. CLKIN can be driven by a CMOS clock.



[‡] For $^{\prime}$ C31, all typical values are at $^{\prime}$ V_{DD} = 5 V, $^{\prime}$ T_A (air temperature) = 25°C. For $^{\prime}$ LC31, all typical values are at $^{\prime}$ V_{DD} = 3.3 V, $^{\prime}$ T_A (air temperature) = 25°C.

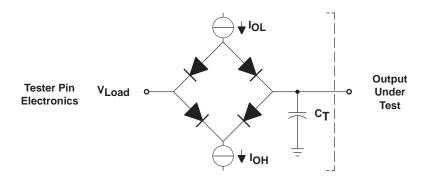
[§] Pins with internal pullup devices: INT3-INT0, MCBL/MP.

Actual operating current is less than this maximum value. This value was obtained under specially produced worst-case test conditions, which are not sustained during normal device operation. These conditions consist of continuous parallel writes of a checkerboard pattern at the maximum rate possible. See *Calculation of TMS320C30 Power Dissipation Application Report* (literature number SPRA020).

 $^{^{\#}\,}f_{X}$ is the input clock frequency.

Specified by design but not tested

PARAMETER MEASUREMENT INFORMATION



Where: = 2 mA (all outputs) lol = 300 μA (all outputs) IOH $V_{LOAD} = 2.15 V$

= 80-pF typical load-circuit capacitance

Figure 4. TMS320C31 Test Load Circuit

signal transition levels for 'C31 (see Figure 5 and Figure 6)

TTL-level outputs are driven to a minimum logic-high level of 2.4 V and to a maximum logic-low level of 0.6 V. Output transition times are specified as follows:

- For a high-to-low transition on a TTL-compatible output signal, the level at which the output is said to be no longer high is 2 V and the level at which the output is said to be low is 1 V.
- For a low-to-high transition, the level at which the output is said to be no longer low is 1 V and the level at which the output is said to be high is 2 V.



Figure 5. TTL-Level Outputs

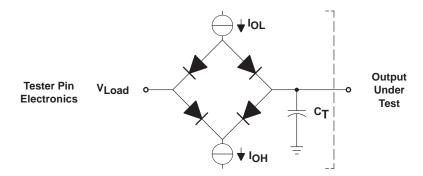
Transition times for TTL-compatible inputs are specified as follows:

- For a high-to-low transition on an input signal, the level at which the input is said to be no longer high is 2 V and the level at which the input is said to be low is 0.8 V.
- For a low-to-high transition on an input signal, the level at which the input is said to be no longer low is 0.8 V and the level at which the input is said to be high is 2 V.



Figure 6. TTL-Level Inputs

PARAMETER MEASUREMENT INFORMATION



Where: I_{OL} = 2 mA (all outputs) I_{OH} = 300 μ A (all outputs)

 $V_{LOAD} = 2.15 V$

C_T = 80-pF typical load-circuit capacitance

Figure 7. TMS320LC31 Test Load Circuit

signal transition levels for 'LC31 (see Figure 8 and Figure 9)

Outputs are driven to a minimum logic-high level of 2 V and to a maximum logic-low level of 0.4 V. Output transition times are specified as follows:

- For a high-to-low transition on an output signal, the level at which the output is said to be no longer high is 2 V and the level at which the output is said to be low is 1 V.
- For a low-to-high transition, the level at which the output is said to be no longer low is 1 V and the level at which the output is said to be high is 2 V.



Figure 8. 'LC31 Output Levels

Transition times for inputs are specified as follows:

- For a high-to-low transition on an input signal, the level at which the input is said to be no longer high is 1.8 V and the level at which the input is said to be low is 0.6 V.
- For a low-to-high transition on an input signal, the level at which the input is said to be no longer low is 0.6 V and the level at which the input is said to be high is 1.8 V.



Figure 9. 'LC31 Input Levels



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PARAMETER MEASUREMENT INFORMATION

timing parameter symbology

Timing parameter symbols used herein were created in accordance with JEDEC Standard 100-A. In order to shorten the symbols, some of the pin names and other related terminology have been abbreviated as follows, unless otherwise noted:

Α	A23-A0	Н	H1 and H3
ASYNCH	Asynchronous reset signals	HOLD	HOLD
С	CLKX0	HOLDA	HOLDA
CI	CLKIN	IACK	IACK
CLKR	CLKR0	INT	INT3-INT0
CONTROL	Control signals	RDY	RDY
D	D31-D0	RW	R/\overline{W}
DR	DR	RESET	RESET
DX	DX	S	STRB
FS	FSX/R	SCK	CLKX/R
FSX	FSX0	SHZ	SHZ
FSR	FSR0	TCLK	TCLK0, TCLK1, or TCLKx
GPI	General-purpose input	XF	XF0, XF1, or XFx
GPIO	General-purpose input/output; peripheral pin	XFIO	XFx switching from input to output
GPO	General-purpose output		



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timing

Timing specifications apply to the TMS320C31 and TMS320LC31.

X2/CLKIN, H1, and H3 timing

The following table defines the timing parameters for the X2/CLKIN, H1, and H3 interface signals. The numbers shown in Figure 10 and Figure 11 correspond with those in the NO. column of the table below.

timing parameters for X2/CLKIN, H1, H3 (see Figure 10 and Figure 11)

NO.			'LC3	31	'C31 'LC3	-	'C31	-50	'C31	-60	'C31	-80	UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
1	t _f (CI)	Fall time, CLKIN		5†		5†		5†		4†		4†	ns
2	tw(CIL)	Pulse duration, CLKIN low $t_{C(CI)} = min$	10		9		7		6		5		ns
3	tw(CIH)	Pulse duration, CLKIN high $t_{C(CI)} = min$	10		9		7		6		5		ns
4	tr(CI)	Rise time, CLKIN		5†		5†		5†		4†		4†	ns
5	t _{c(CI)}	Cycle time, CLKIN	30	303	25	303	20	303	16.67	303	12.5	303	ns
6	t _{f(H)}	Fall time, H1 and H3		3		3		3		3		3	ns
7	tw(HL)	Pulse duration, H1 and H3 low	P-6 [‡]		P-5‡		P-5 [‡]		P-4 [‡]		P-3 [‡]		ns
8	t _{w(HH)}	Pulse duration, H1 and H3 high	P-7‡		P-6‡		P-6‡		P-5 [‡]		P-4 [‡]		ns
9	t _{r(H)}	Rise time, H1 and H3		4		3		3		3		3	ns
10	^t d(HL-HH)	Delay time. from H1 low to H3 high or from H3 low to H1 high	0	5	0	4	0	4	0	4	0	3	ns
11	t _C (H)	Cycle time, H1 and H3	60	606	50	606	40	606	33.3	606	25	606	ns

[†] Specified by design but not tested

 $^{^{\}ddagger}P = t_{C(CI)}$

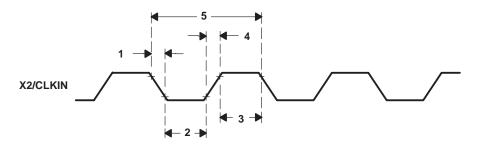


Figure 10. Timing for X2/CLKIN



X2/CLKIN, H1, and H3 timing (continued)

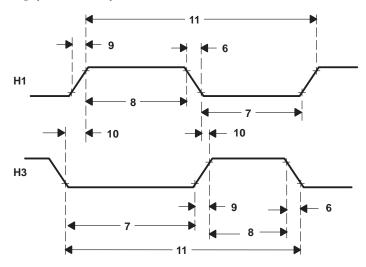


Figure 11. Timing for H1 and H3

timing parameters for memory $(\overline{STRB} = 0)$ read/write (see Figure 12 and Figure 13)[†]

those in the NO. column of the table below.

memory read/write timing

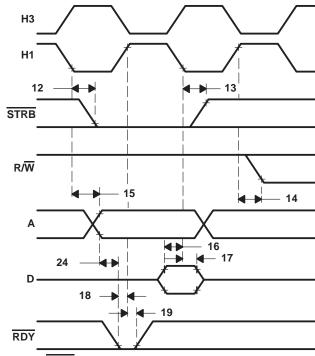
The following table defines memory read/write timing parameters for STRB. The numbers shown in Figure 12 and Figure 13 correspond with

NO.			'LC31-33	'C31-40 'LC31-40	,C31-50	,C31-60	'C31-80	LIND
			MIN MAX	MIN MAX	MIN MAX	MIN MAX	MIN MAX	
12	td(H1L-SL)	Delay time, H1 low to STRB low	0‡ 10	9 ‡0	9 ‡0	9 ‡0	9 ‡0	ns
13	td(H1L-SH)	Delay time, H1 low to STRB high	0‡ 10	9 ‡0	9 ‡0	9 ‡0	9 ‡0	ns
14	td(H1H-RWL)R	Delay time, H1 high to R∕W low (read)	0‡ 10	6 ‡0	2 ‡0	9 ‡0	4 ‡0	su
15	^t d(H1L-A)	Delay time, H1 low to A valid	0‡ 14	0‡ 11	6 ‡0	8 ‡0	2 ‡0	ns
16	^t su(D-H1L)R	Setup time, D before H1 low (read)	16	14	10	6	8	ns
17	th(H1L-D)R	Hold time, D after H1 low (read)	0	0	0	0	0	ns
18	tsu(RDY-H1H)	Setup time, RDY before H1 high	8	8	9	5	4	ns
19	th(H1H-RDY)	Hold time, RDY after H1 high	0	0	0	0	0	ns
20	td(H1H-RWH)W	Delay time, H1 high to RM high (write)	10	6	2	9	4	ns
21	^t v(H1L-D)W	Valid time, D after H1 low (write)	20	17	14	12	8	ns
22	th(H1H-D)W	Hold time, D after H1 high (write)	0	0	0	0	0	ns
23	td(H1H-A)W	Delay time, H1 high to A valid on back-to-back write cycles (write)	18	15	12	10	8	ns
24	td(A-RDY)	Delay time, RDY from A valid	‡8	14	‡ ⁹	‡9	P - 8§	ns
24A	Таа	Address valid to data valid (read)	30	25	21	16	10	ns

[†] See Figure 14 for address bus timing variation with load capacitance greater than typical load-circuit capacitance (C⊤ = 80 pF).

 $^{^{+}}$ This value is characterized but not tested $^{\circ}$ In the subsect of the s

memory read/write timing (continued)



NOTE A: STRB remains low during back-to-back read operations.

Figure 12. Timing for Memory ($\overline{STRB} = 0$) Read

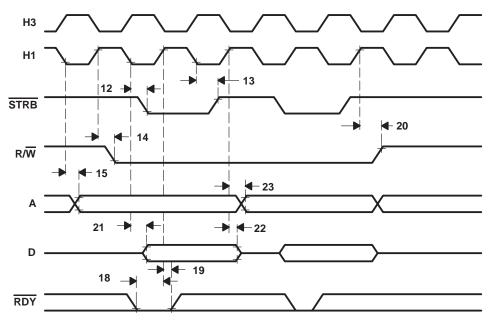


Figure 13. Timing for Memory (STRB = 0) Write



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memory read/write timing (continued)

Address-Bus Timing Variation Load Capacitance Change in Address-Bus Timing, ns 4.00 3.50 3.00 2.50 2.00 1.50 1.00 0.50 10 15 20 25 30 35 40 45 50 55 60 65 70 75 80 85 90 95 100

NOTE A: 30 pF/ns slope

Figure 14. Address-Bus Timing Variation With Load Capacitance (see Note A)

Change in Load Capacitance, pF



XF0 and XF1 timing when executing LDFI or LDII

The following tables define the timing parameters for XF0 and XF1 during execution of LDFI or LDII. The numbers shown in Figure 15 correspond with those in the NO. column of the tables below.

timing parameters for XF0 and XF1 when executing LDFI or LDII for TMS320C31 (see Figure 15)

NO.			'LC3	31-33	'C31 'LC3	-	,C3,	I- 5 0	'C3	1-60	'C31	l - 80	UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
25	td(H3H-XF0L)	Delay time, H3 high to XF0 low		15		13		12		11		8	ns
26	tsu(XF1-H1L)	Setup time, XF1 before H1 low	10		9		9		8		6		ns
27	th(H1L-XF1)	Hold time, XF1 after H1 low	0		0		0		0		0		ns

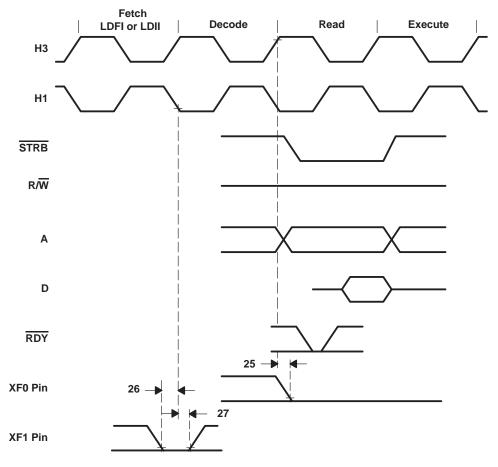


Figure 15. Timing for XF0 and XF1 When Executing LDFI or LDII

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XF0 timing when executing STFI and STII[†]

The following table defines the timing parameters for the XF0 pin during execution of STFI or STII. The number shown in Figure 16 corresponds with the number in the NO. column of the table below.

timing parameters for XF0 when executing STFI or STII (see Figure 16)

NO.			'LC3	31-33	'C31 'LC3	-	,C3,	1-50	,C3,	1-60	'C3	I - 80	UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
28	^t d(H3H-XF0H)	Delay time, H3 high to XF0 high		15		13		12		11		8	ns

TXF0 is always set high at the beginning of the execute phase of the interlock-store instruction. When no pipeline conflicts occur, the address of the store is also driven at the beginning of the execute phase of the interlock-store instruction. However, if a pipeline conflict prevents the store from executing, the address of the store will not be driven until the store can execute.

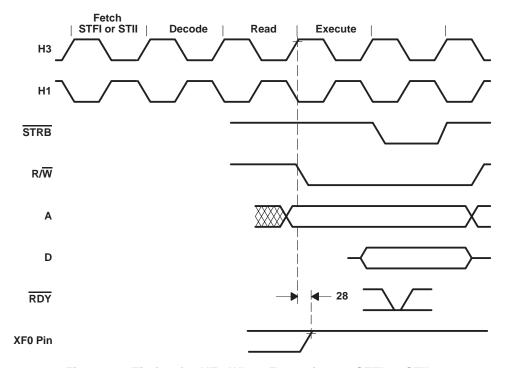


Figure 16. Timing for XF0 When Executing an STFI or STII

XF0 and XF1 timing when executing SIGI

The following tables define the timing parameters for the XF0 and XF1 pins during execution of SIGI. The numbers shown in Figure 17 correspond with those in the NO. column of the tables below.

timing parameters for XF0 and XF1 when executing SIGI for TMS320C31 (see Figure 17)

NO.			'LC3	1-33	'C31 'LC3	-	,C3,	1-50	'C3	1-60	'C31	-80	UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
29	td(H3H-XF0L)	Delay time, H3 high to XF0 low		15		13		12		11		8	ns
30	td(H3H-XF0H)	Delay time, H3 high to XF0 high		15		13		12		11		8	ns
31	t _{su(XF1-H1L)}	Setup time, XF1 before H1 low	10		9		9		8		6		ns
32	^t h(H1L-XF1)	Hold time, XF1 after H1 low	0		0		0		0		0		ns

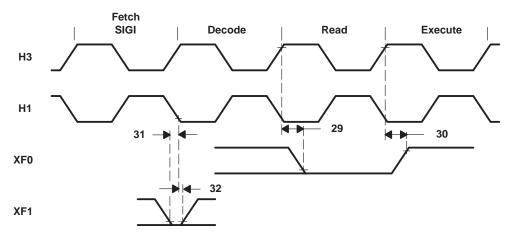


Figure 17. Timing for XF0 and XF1 When Executing SIGI

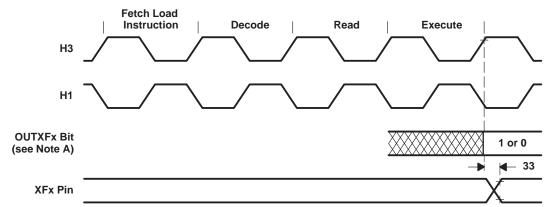
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loading when XF is configured as an output

The following table defines the timing parameter for loading the XF register when the XFx pin is configured as an output. The number shown in Figure 18 corresponds with the number in the NO. column of the table below.

timing parameters for loading the XF register when configured as an output pin (see Figure 18)

NO.			'LC3	31-33	'C31 'LC3	-40 1-40	,C3,	1-50	,C3,	1-60	'C3	I-80	UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
33	t _V (H3H-XF)	Valid time, H3 high to XFx		15		13		12		11		8	ns



NOTE A: OUTXFx represents either bit 2 or 6 of the IOF register.

Figure 18. Timing for Loading XF Register When Configured as an Output Pin



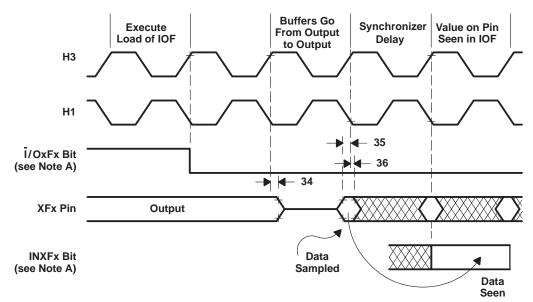
changing XFx from an output to an input

The following table defines the timing parameters for changing the XFx pin from an output pin to an input pin. The numbers shown in Figure 19 correspond with those in the NO. column of the table below.

timing parameters of XFx changing from output to input mode for TMS320C31 (see Figure 19)

NO.			'LC3	1-33	'C31- 'LC3		'C31	-50	'C31	-60	'C31	-80	UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
34	^t h(H3H-XF)	Hold time, XFx after H3 high		15†		13†		12†		11†		9†	ns
35	^t su(XF-H1L)	Setup time, XFx before H1 low	10		9		9		8		6		ns
36	^t h(H1L-XF)	Hold time, XFx after H1 low	0	·	0	·	0	·	0		0	·	ns

[†] This value is characterized but not tested.



NOTE A: Ī/OxFx represents either bit 1 or bit 5 of the IOF register, and INXFx represents either bit 3 or bit 7 of the IOF register.

Figure 19. Timing for Change of XFx From Output to Input Mode



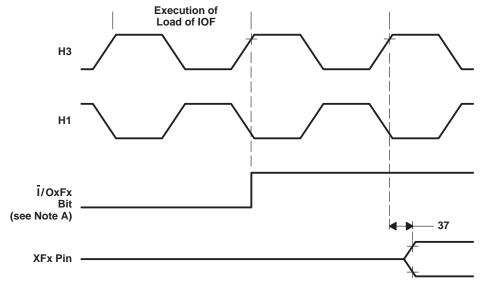
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changing XFx from an input to an output

The following table defines the timing parameter for changing the XFx pin from an input pin to an output pin. The number shown in Figure 20 corresponds with the number in the NO. column of the table below.

timing parameters of XFx changing from input to output mode (see Figure 20)

NO.			'LC3	31-33	'C31 'LC3	-40 1-40	,C3,	1-50	'C3	1-60	'C31	I-80	UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
37	td(H3H-XFIO)	Delay time, H3 high to XFx switching from input to output		20		17		17		16		9	ns



NOTE A: I/OxFx represents either bit 1 or bit 5 of the IOF register.

Figure 20. Timing for Change of XFx From Input to Output Mode

reset timing

RESET is an asynchronous input that can be asserted at any time during a clock cycle. If the specified timings are met, the exact sequence shown in Figure 21 occurs; otherwise, an additional delay of one clock cycle is possible.

The asynchronous reset signals include XF0/1, CLKX0, DX0, FSX0, CLKR0, DR0, FSR0, and TCLK0/1.

The following table defines the timing parameters for the RESET signal. The numbers shown in Figure 21 correspond with those in the NO. column of the following table.

Resetting the device initializes the bus control register to seven software wait states and therefore results in slow external accesses until these registers are initialized.

HOLD is an asynchronous input and can be asserted during reset.

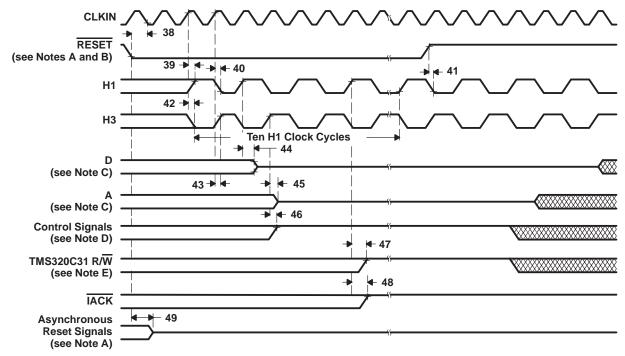


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NO.			'LC31-33	-33	'C31-40 'LC31-40	0 40	'LC31-40	40	,C31-50	50	'C31-60	09-	,C31-80	80	TINO
			NIM	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
38	tsu(RESET-CIL)	Setup time, <u>RESET</u> before CLKIN low	10	P†‡	10	P‡‡	10	P‡‡	10	p†‡	7	P†‡	4	P†‡	ns
39	td(CLKINH-H1H)	Delay time, CLKIN high to H1 high§	2	12	2	12¶	2	14	2	10	2	10	2	8	ns
40	td(CLKINH-H1L)	Delay time, CLKIN high to H1 low§	2	12	2	12¶	2	14	2	10	2	10	2	8	ns
41	^t su(RESETH-H1L)	Setup time, RESET high before H1 low and after ten H1 clock cycles	10		6		6		7		9		5		ns
42	td(CLKINH-H3L)	Delay time, CLKIN high to H3 low§	2	12¶	2	12	2	14	2	10	2	10	2	8	ns
43	td(CLKINH-H3H)	Delay time, CLKIN high to H3 high§	2	12¶	2	12	2	14	2	10	2	10	2	8	ns
44	tdis(H1H-DZ)	Disable time, H1 high to D (high impedance)		15#		13#		13#		12#		11#		#6	ns
45	tdis(H3H-AZ)	Disable time, H3 high to A (high impedance)		10#		#6		#6		#8		#2		#9	ns
46	td(H3H-CONTROLH)	Delay time, H3 high to control signals high		10#		#6		#6		#8		#2		#9	ns
47	td(H1H-RWH)	Delay time, H1 high to R/W high		10#		#6		#6		#8		#4		#9	ns
48	^t d(H1H-IACKH)	Delay time, H1 high to <u>IACK</u> high		10#		#6		#6		#8		#2		#9	ns
49	tdis(RESETL-ASYNCH)	Disable time, RESET low to asynchronous reset signals disabled (high impedance)		25#		21#		21#		17#		14#		12#	ns
+															

† P = t_C(CI) ‡ Specified by design but not tested \$ See Figure 22 for temperature dependence . ¶ 14 ns for the extended temperature 'C31-40 # This value is characterized but not tested

timing parameters for RESET for the TMS320C31 and TMS320LC31 (continued)



NOTES: A. Asynchronous reset signals include XF0/1, CLKX0, DX0, FSX0, CLKR0, DR0, FSR0, and TCLK0/1.

- B. RESET is an asynchronous input and can be asserted at any point during a clock cycle. If the specified timings are met, the exact sequence shown occurs; otherwise, an additional delay of one clock cycle is possible.
- C. In microprocessor mode, the reset vector is fetched twice, with seven software wait states each time. In microcomputer mode, the reset vector is fetched twice, with no software wait states.
- D. Control signals include STRB.
- E. The $R\overline{W}$ outputs are placed in a high-impedance state during reset and can be provided with a resistive pullup, nominally $18-22 \text{ k}\Omega$, if undesirable spurious writes are caused when these outputs go low.

Figure 21. Timing for RESET

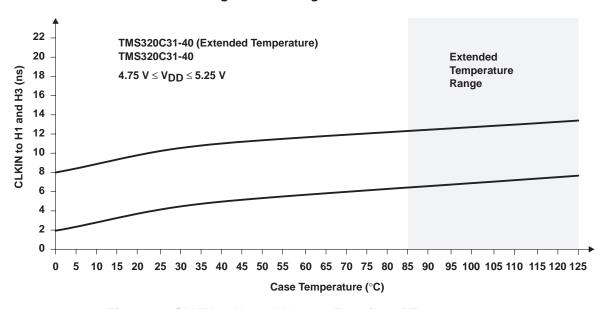


Figure 22. CLKIN to H1 and H3 as a Function of Temperature

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interrupt response timing

The following table defines the timing parameters for the $\overline{\text{INT}}$ signals. The numbers shown in Figure 23 correspond with those in the NO. column of the table below.

timing parameters for INT3-INT0 response (see Figure 23)

NO.			'LC3	1-33	'C31- 'LC3	-	'C31	-50	'C31	-60	'C31	-80	UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
50	^t su(INT-H1L)	Setup time, INT3– INT0 before H1 low	15		13		10		8		5		ns
51	t _w (INT)	Pulse duration, interrupt to ensure only one interrupt	Р	2P†‡	Р	2P†‡	Р	2P†‡	Р	2P†‡	Р	2P†‡	ns

[†] This value is characterized but not tested.

The interrupt (INT) pins are asynchronous inputs that can be asserted at any time during a clock cycle. The TMS320C3x interrupts are level-sensitive, not edge-sensitive. Interrupts are detected on the falling edge of H1. Therefore, interrupts must be set up and held to the falling edge of H1 for proper detection. The CPU and DMA respond to detected interrupts on instruction-fetch boundaries only.

For the processor to recognize only one interrupt on a given input, an interrupt pulse must be set up and held to:

- A minimum of one H1 falling edge
- No more than two H1 falling edges

The TMS320C3x can accept an interrupt from the same source every two H1 clock cycles.

If the specified timings are met, the exact sequence shown in Figure 23 occurs; otherwise, an additional delay of one clock cycle is possible.



 $P = t_{C(H)}$

timing parameters for INT3-INT0 response (continued)

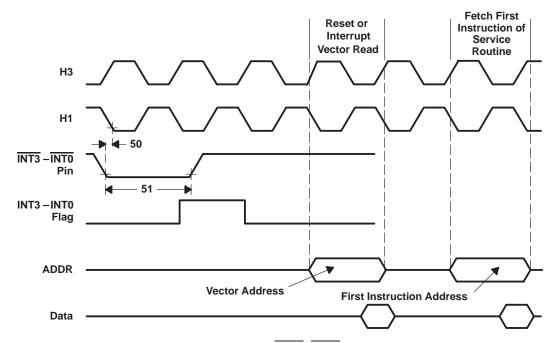


Figure 23. Timing for INT3-INT0 Response

interrupt-acknowledge timing

The IACK output goes active on the first half-cycle (HI rising) of the decode phase of the IACK instruction and goes inactive at the first half-cycle (HI rising) of the read phase of the IACK instruction.

The following table defines the timing parameters for the IACK signal. The numbers shown in Figure 24 correspond with those in the NO. column of the table below.

timing parameters for IACK (see Note 7 and Figure 24)

NO.			'LC3	1-33	'C3′ 'LC3	-	,C3,	1-50	'C3	1-60	,C3,	I-80	UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
52	^t d(H1H-IACKL)	Delay time, H1 high to IACK low		10		9		7		6		5	ns
53	^t d(H1H-IACKH)	Delay time, H1 high to IACK high		10		9		7		6		5	ns

NOTE 7: IACK goes active on the first half-cycle (H1 rising) of the decode phase of the IACK instruction and goes inactive at the first half-cycle (H1 rising) of the read phase of the IACK instruction. Because of pipeline conflicts, IACK remains low for one cycle even if the decode phase of the IACK instruction is extended.

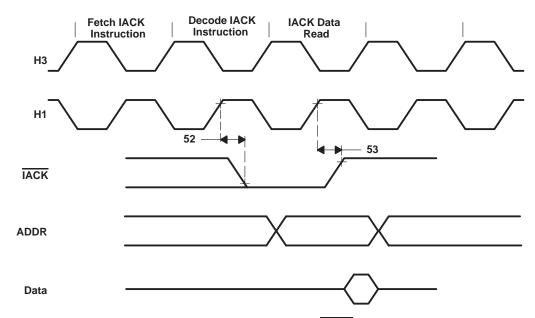


Figure 24. Timing for IACK

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serial-port timing parameters for TMS320C31-33 and TMS320LC31-33 (see Figure 25 and Figure 26)

NO				'LC3	1-33	UNIT
NO.				MIN	MAX	UNII
54	td(H1H-SCK)	Delay time, H1 high to internal CLKX/R			15	ns
55	t (221)	Cycle time, CLKX/R	CLKX/R ext	t _{C(H)} x2.6		20
55	t _C (SCK)	Cycle time, CLRA/R	CLKX/R int	t _{c(H)} x2	t _{c(H)} x2 ³²	ns
56		Pulse duration, CLKX/R high/low	CLKX/R ext	t _{C(H)} +12		ns
56	tw(SCK)	Fulse duration, CERX/R high/low	CLKX/R int	[t _{C(SCK)} /2]-15	[t _{C(SCK)} /2]+5	115
57	tr(SCK)	Rise time, CLKX/R			8	ns
58	tf(SCK)	Fall time, CLKX/R			8	ns
59	.	Delay time, CLKX to DX valid	CLKX ext		35	
59	^t d(C-DX)	Delay time, CLKX to DX valid	CLKX int		20	ns
60		Catura time a DD hafara CLVD law	CLKR ext	10		
60	tsu(DR-CLKRL)	Setup time, DR before CLKR low	CLKR int	25		ns
64		Hald time DD from CLKD law	CLKR ext	10		
61	th(CLKRL-DR)	Hold time, DR from CLKR low	CLKR int	0		ns
60	4	Polonitimo CLIVV to internal ECV high/land	CLKX ext		32	
62	td(C-FSX)	Delay time, CLKX to internal FSX high/low	CLKX int		17	ns
63		Setup time, FSR before CLKR low	CLKR ext	10		
03	tsu(FSR-CLKRL)	Setup time, FSR before CLRR low	CLKR int	10		ns
64		Hold time FCV/D input from CLVV/D law	CLKX/R ext	10		
64	th(SCKL-FS)	Hold time, FSX/R input from CLKX/R low	CLKX/R int	0		ns
65		Coture time a cutomad ECV before CLVV	CLKX ext	-[t _{c(H)} -8] [†]	[t _C (SCK)/2]-10 [†]	
65	tsu(FSX-C)	Setup time, external FSX before CLKX	CLKX int	[t _{c(H)} -21] [†]	t _{c(SCK)} /2†	ns
66		Delay time, CLKX to first DX bit, FSX	CLKX ext		36†	
66	td(CH-DX)V	precedes CLKX high	CLKX int		21 [†]	ns
67	^t d(FSX-DX)V	Delay time, FSX to first DX bit, CLKX precede	es FSX		36†	ns
68	^t d(CH-DXZ)	Delay time, CLKX high to DX high impedance bit	following last data		20†	ns

[†] This value is characterized but not tested

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serial-port timing parameters for TMS320C31-40 and TMS320LC31-40 (see Figure 25 and Figure 26)

NO.					1-40 31-40	UNIT
				MIN	MAX	
54	td(H1H-SCK)	Delay time, H1 high to internal CLKX/R			13	ns
55	t (2010	Cycle time, CLKX/R	CLKX/R ext	t _{c(H)} x2.6		ns
33	tc(SCK)	Cycle time, GLRA/R	CLKX/R int	t _{c(H)} x2	t _C (H)X232	10
56	t (00)	Pulse duration, CLKX/R high/low	CLKX/R ext	t _{C(H)} +10		ns
36	tw(SCK)	Fulse duration, CERA/R high/low	CLKX/R int	[t _{C(SCK)} /2]-5	[t _{C(SCK)} /2]+5	10
57	tr(SCK)	Rise time, CLKX/R			7	ns
58	tf(SCK)	Fall time, CLKX/R			7	ns
59		Delevatime CLKV to DV volid	CLKX ext		30	
59	^t d(C-DX)	Delay time, CLKX to DX valid	CLKX int		17	ns
60		Catua time DD before CLVD law	CLKR ext	9		
60	^t su(DR-CLKRL)	Setup time, DR before CLKR low	CLKR int	21		ns
61		Hold time DD from CLKD low	CLKR ext	9		
01	th(CLKRL-DR)	Hold time, DR from CLKR low	CLKR int	0		ns
62		Delevations CLIVV to internal FCV high/low	CLKX ext		27	
02	td(C-FSX)	Delay time, CLKX to internal FSX high/low	CLKX int		15	ns
63		Setup time, FSR before CLKR low	CLKR ext	9		
03	tsu(FSR-CLKRL)	Setup time, FSR before CLRR low	CLKR int	9		ns
64	t. (0.01(1. =0)	Hold time, FSX/R input from CLKX/R low	CLKX/R ext	9		ns
04	th(SCKL-FS)	Hold time, F3X/K input from CERX/K low	CLKX/R int	0		110
65	t (=0)(o)	Setup time, external FSX before CLKX	CLKX ext	-[t _{C(H)} -8]†	[t _{C(SCK)} /2]-10 [†]	ns
0.5	tsu(FSX-C)	Setup time, external 1 37 before CENA	CLKX int	[t _{C(H)} -21] [†]	t _{c(SCK)} /2†	110
66		Delay time, CLKX to first DX bit, FSX	CLKX ext		30†	20
00	td(CH-DX)V	precedes CLKX high	CLKX int		₁₈ †	ns
67	td(FSX-DX)V	Delay time, FSX to first DX bit, CLKX precede	es FSX		30†	ns
68	^t d(CH-DXZ)	Delay time, CLKX high to DX high impedance bit	e following last data		17†	ns

[†] This value is characterized but not tested

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serial-port timing parameters for TMS320C31-50 (see Figure 25 and Figure 26)

NO.				,C3	'C31-50	
NO.				MIN	MAX	UNIT
54	td(H1H-SCK)	Delay time, H1 high to internal CLKX/R			10	ns
55	t _C (SCK)	Cycle time, CLKX/R	CLKX/R ext	t _{c(H)} x2.6		ns
			CLKX/R int	t _{c(H)} x2	t _{C(H)} x2 ³²	
56	tw(SCK)	Pulse duration, CLKX/R high/low	CLKX/R ext	t _{C(H)} +10		ns
30			CLKX/R int	[t _{c(SCK)} /2]-5	[t _{C(SCK)} /2]+5	
57	tr(SCK)	Rise time, CLKX/R			6	ns
58	tf(SCK)	Fall time, CLKX/R			6	ns
59	^t d(C-DX)	Delay time, CLKX to DX valid	CLKX ext		24	ns
39			CLKX int		16	
60	^t su(DR-CLKRL)	Setup time, DR before CLKR low	CLKR ext	9		ns
60			CLKR int	17		
61	^t h(CLKRL-DR)	Hold time, DR from CLKR low	CLKR ext	7		ns
61			CLKR int	0		
62	td(C-FSX)	Delay time, CLKX to internal FSX high/low	CLKX ext		22	ns
62			CLKX int		15	
63	^t su(FSR-CLKRL)	Setup time, FSR before CLKR low	CLKR ext	7		ns
63			CLKR int	7		
64	th(SCKL-FS)	FS) Hold time, FSX/R input from CLKX/R low	CLKX/R ext	7		ns
64			CLKX/R int	0		
65	t _{su(FSX-C)}	Setup time, external FSX before CLKX	CLKX ext	-[t _{C(H)} -8]†	[t _{c(SCK)} /2]-10 [†]	ns
65			CLKX int	-[t _{C(H)} -21] [†]	t _{c(SCK)} /2†	
66	td(CH-DX)V	Delay time, CLKX to first DX bit, FSX precedes CLKX high	CLKX ext		24†	ns
00			CLKX int		14†	
67	td(FSX-DX)V	Delay time, FSX to first DX bit, CLKX precedes FSX			24†	ns
68	t _d (CH-DXZ)	Delay time, CLKX high to DX high impedance following last data bit			14†	ns

[†] This value is characterized but not tested



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serial-port timing parameters for TMS320C31-60 (see Figure 25 and Figure 26)

NO				'C31-60		LINUT	
NO.				MIN	MAX	UNIT	
54	td(H1H-SCK)	Delay time, H1 high to internal CLKX/R			8	ns	
55	t _c (SCK)	Cycle time, CLKX/R	CLKX/R ext	t _{C(H)} x2.6		ns	
			CLKX/R int	t _{c(H)} x2	t _{c(H)} x2 ³²		
56	tw(SCK)	Pulse duration, CLKX/R high/low	CLKX/R ext	t _{C(H)} +10		ns	
36			CLKX/R int	[t _{c(SCK)} /2]-5	[t _{C(SCK)} /2]+5		
57	tr(SCK)	Rise time, CLKX/R			5	ns	
58	tf(SCK)	Fall time, CLKX/R			5	ns	
59		Delay time, CLKX to DX valid	CLKX ext		20	ns	
59	^t d(C-DX)		CLKX int		15		
60	^t su(DR-CLKRL)	Setup time, DR before CLKR low	CLKR ext	8		ns	
60			CLKR int	15			
C4		Hold time, DR from CLKR low	CLKR ext	6		ns	
61	th(CLKRL-DR)		CLKR int	0			
-00	td(C-FSX)	Delay time, CLKX to internal FSX high/low	CLKX ext		20	ns	
62			CLKX int		14		
63	^t su(FSR-CLKRL)	Setup time, FSR before CLKR low	CLKR ext	6		ns	
03			CLKR int	6			
64	^t h(SCKL-FS)	Hold time, FSX/R input from CLKX/R low	CLKX/R ext	6		ns	
04			CLKX/R int	0			
65	t _{su(FSX-C)}	Setup time, external FSX before CLKX	CLKX ext	-[t _{C(H)} -8] [†]	[t _{C(SCK)} /2]-10 [†]	ns	
00			CLKX int	-[t _{C(H)} -21] [†]	t _{c(SCK)} /2 [†]		
	td(CH-DX)V	Delay time, CLKX to first DX bit, FSX precedes CLKX high	CLKX ext	1	20†	ns	
66			CLKX int		12†		
67	^t d(FSX-DX)V	Delay time, FSX to first DX bit, CLKX precedes FSX			20†	ns	
68	^t d(CH-DXZ)	Delay time, CLKX high to DX high impedance following last data bit			12†	ns	

[†] This value is characterized but not tested

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serial-port timing parameters for TMS320C31-80 (see Figure 25 and Figure 26)

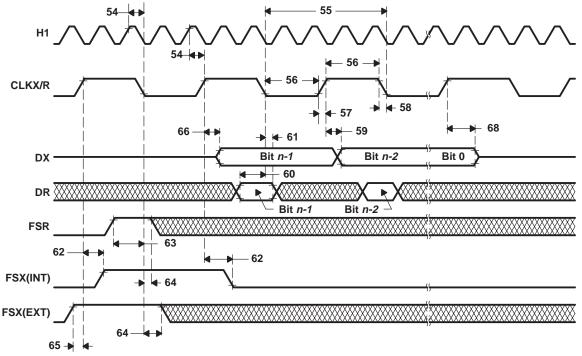
NO.				'C31-80		UNIT	
NO.				MIN	MAX	UNII	
54	td(H1H-SCK)	Delay time, H1 high to internal CLKX/R			7	ns	
55	tc(SCK)	Cycle time, CLKX/R	CLKX/R ext	t _{C(H)} x2.6		ns	
			CLKX/R int	t _{C(H)} x2	t _{c(H)} x2 ³²		
56	tw(SCK)	Pulse duration, CLKX/R high/low	CLKX/R ext	t _{C(H)} +6		ns	
30			CLKX/R int	[t _{C(SCK)} /2]-5	[t _{C(SCK)} /2]+5		
57	tr(SCK)	Rise time, CLKX/R			3	ns	
58	tf(SCK)	Fall time, CLKX/R			3	ns	
59		Delay time, CLKX to DX valid	CLKX ext		16	ns	
59	^t d(C-DX)		CLKX int		11		
60	^t su(DR-CLKRL)	Setup time, DR before CLKR low	CLKR ext	6		ns	
60			CLKR int	13			
64	^t h(CLKRL-DR)	Hold time, DR from CLKR low	CLKR ext	5		ns	
61			CLKR int	0			
60	td(C-FSX)	Delay time, CLKX to internal FSX high/low	CLKX ext		16	ns	
62			CLKX int		12		
63	^t su(FSR-CLKRL)	Setup time, FSR before CLKR low	CLKR ext	5		ns	
03			CLKR int	5			
64	th(SCKL-FS)	FS) Hold time, FSX/R input from CLKX/R low	CLKX/R ext	5		ns	
64			CLKX/R int	0			
65	^t su(FSX-C)	Setup time, external FSX before CLKX	CLKX ext	-[t _{c(H)} -8] [†]	[t _C (SCK)/2]-10 [†]	ns	
65			CLKX int	-[t _{c(H)} -21] [†]	t _{c(SCK)} /2 [†]		
66	td(CH-DX)V	Delay time, CLKX to first DX bit, FSX precedes CLKX high	CLKX ext		16	ns	
66			CLKX int		10		
67	^t d(FSX-DX)V	Delay time, FSX to first DX bit, CLKX precedes FSX			16	ns	
68	^t d(CH-DXZ)	Delay time, CLKX high to DX high impedance following last data bit			10	ns	

[†] This value is characterized but not tested

data-rate timing modes

Unless otherwise indicated, the data-rate timings shown in Figure 25 and Figure 26 are valid for all serial-port modes, including handshake. For a functional description of serial-port operation refer to subsection 8.2.12 of the *TMS320C3x User's Guide* (literature number SPRU031).

The serial-port timing parameters for seven 'C3x devices are defined in the preceding "serial-port timing parameters" tables (such as "serial-port timing parameters for TMS320C31-60"). The numbers shown in Figure 25 and Figure 26 correspond with those in the NO. column of each table.



NOTES: A. Timing diagrams show operations with CLKXP = CLKRP = FSXP = FSRP = 0.

B. Timing diagrams depend on the length of the serial-port word, where n = 8, 16, 24, or 32 bits, respectively.

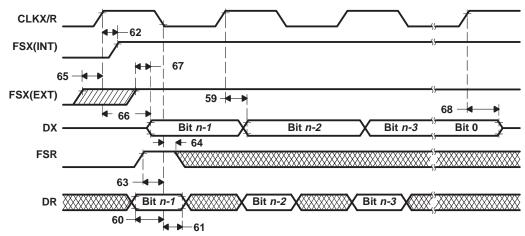
Figure 25. Timing for Fixed Data-Rate Mode



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data-rate timing modes (continued)



NOTES: A. Timing diagrams show operation with CLKXP = CLKRP = FSXP = FSRP = 0.

- B. Timing diagrams depend on the length of the serial-port word, where n = 8, 16, 24, or 32 bits, respectively.
- C. The timings that are not specified expressly for the variable data-rate mode are the same as those that are specified for the fixed data-rate mode.

Figure 26. Timing for Variable Data-Rate Mode



HOLD timing

HOLD is an asynchronous input that can be asserted at any time during a clock cycle. If the specified timings are met, the exact sequence shown in Figure 27 occurs; otherwise, an additional delay of one clock cycle is possible. The table, "timing parameters for HOLD/HOLDA", defines the timing parameters for the HOLD and HOLDA signals. The numbers shown in Figure 27 correspond with those in the NO. column of the table. The NOHOLD bit of the primary-bus control register overrides the HOLD signal. When this bit is set, the device comes out of hold and prevents future hold cycles. Asserting HOLD prevents the processor from accessing the primary bus. Program execution continues until a read from or a write to the primary bus is requested. In certain circumstances, the first write is pending, thus allowing the processor to continue until a second write is encountered.

timing parameters for HOLD/HOLDA (see Figure 27)

ON.	_		.LC31-33		'C31-40 'LC31-40) 40	'C31-50	0	,C31-60		'C31-80		TINO
			MIN	MAX	MIN	MAX	MIN	MAX	MIN MAX	×	MIN	MAX	
69	tsu(HOLD-H1L)	Setup time, HOLD before H1 low	15	Г	13		10		8	H	5		ns
02	tv(H1L-HOLDA)	Valid time, HOLDA after H1 low	‡0	10	10	6	10	7	10	9	10	2	ns
71	tw(HOLD) [‡]	Pulse duration, HOLD low	2t _c (H)		2t _c (H)		2t _{c(H)}		2t _{c(H)}	2	2t _{c(H)}		ns
72	tw(HOLDA)	Pulse duration, HOLDA low	t _{cH} –5†		t _{CH} -5†		t _{cH} -5†		t _{cH} -5†	tc	t _{cH} –5†		ns
23	td(H1L-SH)H	Delay time, H1 low to STRB high for a HOLD	§0	10	§0	6	§0	7	§0	9	§0	4	ns
74	tdis(H1L-S)	Disable time, H1 low to <u>STRB</u> to the high-impedance state	§0	10†	§0	16	§0	8	<u> </u>	71	§0	7	ns
92	ten(H1L-S)	Enable time, H1 low to STRB enabled (active)	§0	10	§0	6	§0	7	§0	9	§0	9	ns
92	^t dis(H1L-RW)	Disable time, H1 low to R/\overline{W} to the high-impedance state	‡0	10†	0†	16	01	81	0†	71	10	et	ns
22	ten(H1L-RW)	Enable time, H1 low to R/W enabled (active)	10	10	10	6	10	7	10	9	0†	9	ns
82	^t dis(H1L-A)	Disable time, H1 low to address to the high-impedance state	§0	10†	§0	101	§0	81	<u>\$</u> 0	71	§0	7	ns
62	ten(H1L-A)	Enable time, H1 low to address enabled (valid)	§0	15	§0	13	§0	12	§0	11	§0	10	ns
08	tdis(H1H-D)	Disable time, H1 high to data to the high-impedance state	§0	101	§0	91	§0	81	<u>s</u> 0	71	§0	6†	ns
T This	Lotoot to a tid botizotoorodo oi oillow oidt +	1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1											

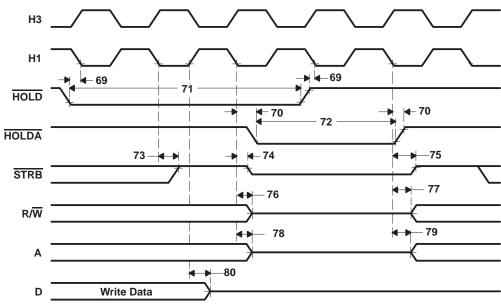
This value is characterized but not tested

HOLD is an asynchronous input and can be asserted at any point during a clock cycle. If the specified timings are met, the exact sequence shown in Figure 27 occurs; otherwise, an additional delay of one clock cycle is possible.

§ Not tested



HOLD timing (continued)



NOTE A: HOLDA goes low in response to HOLD going low and continues to remain low until one H1 cycle after HOLD goes back high.

Figure 27. Timing for HOLD/HOLDA



general-purpose I/O timing

Peripheral pins include CLKX0, CLKR0, DX0, DR0, FSX0, FSR0, and TCLK0/1. The contents of the internal control registers associated with each peripheral define the modes for these pins.

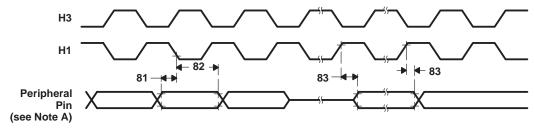
peripheral pin I/O timing

The table, timing parameters for peripheral pin general-purpose I/O, defines peripheral pin general-purpose I/O timing parameters. The numbers shown in Figure 28 correspond with those in the NO. column of the table below.

timing parameters for peripheral pin general-purpose I/O (see Note 8 and Figure 28)

NO.			LC3	1-33	'C31 'LC3	-	'C31	-50	'C31	-60	'C31	-80	UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
81	t _{su} (GPIO-H1L)	Setup time, general-purpose input before H1 low	12		10		9		8		7		ns
82	^t h(H1L-GPIO)	Hold time, general-purpose input after H1 low	0		0		0		0		0		ns
83	^t d(H1H-GPIO)	Delay time, general-purpose output after H1 high		15		13		10		8		6	ns

NOTE 8: Peripheral pins include CLKX0, CLKR0, DX0, DR0, FSX0, FSR0, and TCLK0/1. The modes of these pins are defined by the contents of internal-control registers associated with each peripheral.



NOTE A: Peripheral pins include CLKX0, CLKR0, DX0, DR0, FSX0, FSR0, and TCLK0/1.

Figure 28. Timing for Peripheral Pin General-Purpose I/O



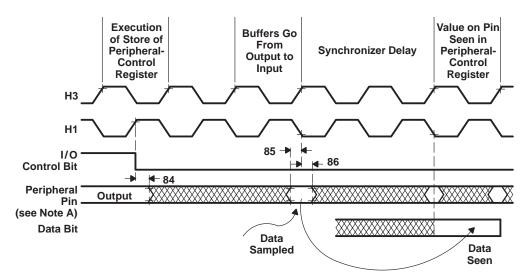
changing the peripheral pin I/O modes

The following tables show the timing parameters for changing the peripheral pin from a general-purpose output pin to a general-purpose input pin and vice versa. The numbers shown in Figure 29 and Figure 30 correspond to those shown in the NO. column of the tables below.

timing parameters for peripheral pin changing from general-purpose output to input mode (see Note 8 and Figure 29)

NO.			'LC3	1-33	'C31 'LC3	-40 1-40	,C3,	1-50	'C31	1-60	'C31	I-80	UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
84	^t h(H1H)	Hold time, peripheral pin after H1 high		15		13		10		8		6	ns
85	t _{su} (GPIO-H1L)	Setup time, peripheral pin before H1 low	10		9		9		8		7		ns
86	^t h(H1L-GPIO)	Hold time, peripheral pin after H1 low	0		0		0		0	·	0		ns

NOTE 8: Peripheral pins include CLKX0, CLKR0, DX0, DR0, FSX0, FSR0, and TCLK0/1. The modes of these pins are defined by the contents of internal-control registers associated with each peripheral.



NOTE A: Peripheral pins include CLKX0, CLKR0, DX0, DR0, FSX0, FSR0, and TCLK0/1.

Figure 29. Timing for Change of Peripheral Pin From General-Purpose Output to Input Mode

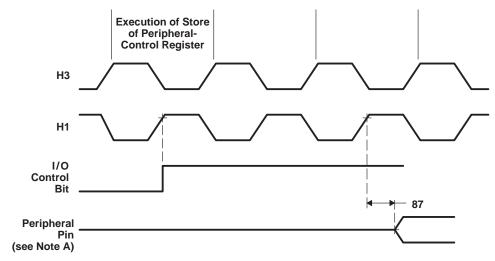


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timing parameters for peripheral pin changing from general-purpose input to output mode (see Note 8 and Figure 30)

NO.			'LC3	1-33	'C31 'LC3	-40 1-40	' C 31	-50	'C31	I -60	'C31	-80	UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
87	^t d(H1H-GPIO)	Delay time, H1 high to peripheral pin switching from input to output		15		13		10		8		6	ns

NOTE 8: Peripheral pins include CLKX0, CLKR0, DX0, DR0, FSX0, FSR0, and TCLK0/1. The modes of these pins are defined by the contents of internal-control registers associated with each peripheral.



NOTE A: Peripheral pins include CLKX0, CLKR0, DX0, DR0, FSX0, FSR0, and TCLK0/1.

Figure 30. Timing for Change of Peripheral Pin From General-Purpose Input to Output Mode



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Valid logic-level periods and polarity are specified by the contents of the internal control registers.

timer pin timing

The following tables define the timing parameters for the timer pin. The numbers shown in Figure 31 correspond with those in the NO. column of the tables below.

timing parameters for timer pin for TMS320LC31-33 (see Figure 31) [†]

NO.		DESCRIPTION [‡]		,LC31-33	-33	'C31-40, 'LC31-40	.0, .40	LINO
				NIM	MAX	MIN	MAX	
88	tsu(TCLK-H1L)	88 tsu(TCLK-H1L) Setup time, TCLK external before H1 low		12		10		su
89	th(H1L-TCLK)	89 th(H1L-TCLK) Hold time, TCLK external after H1 low		0		0		ns
06	td(H1H-TCLK)	td(Н1Н-ТСLK) Delay time, H1 high to TCLK internal valid			10		6	ns
5	;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;	7 OT comit class	TCLK ext	t _{c(H)} ×2.6		t _c (H)×2.6		i S
5	a l (CLK)	Cycle lille, TCEN	TCLK int	$^{\text{t}_{\text{c}}(\text{H})\times2}$	t _C (H)×2 ^{32‡}	t _C (H)×2	tc(H)×232‡	2
S	;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;;	de la constant de la	TCLK ext	t _{C(H)} +12		t _{c(H)} +10		Ç
36	32 w(TCLK)	rdise dalatioli, TOEN IIIgiviow	TCLK int	[tc(TCLK)/2]-15	[tc(TCLK)/2]+5	TCLK int $ [t_c(TCLK)/2]-15$ $[t_c(TCLK)/2]+5$ $ [t_c(TCLK)/2]-5$ $[t_c(TCLK)/2]+5$	[tc(TCLK)/2]+5	SI
 - -								

Timing parameters 88 and 89 are applicable for a synchronous input clock. Timing parameters 91 and 92 are applicable for an asynchronous input clock.

‡ Specified by design but not tested

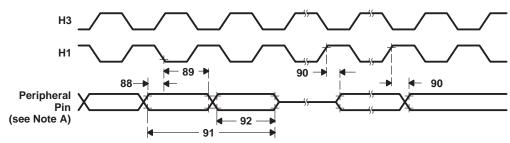
timing parameters for timer pin for TMS320LC31-40, TMS320C31-50, and TMS320C31-60 (see Figure 31) [†]

LINI	5	su	su	su	ç	2	Ġ	2	
30	MAX			9		t _C (H)×2 ^{32‡}		$[t_{c}(TCLK)/2]+5$	
'C31-80	MIN	5	0		t _C (H)×2.6	t _c (H)×2	t _{c(H)} +6	$[t_{c}(TCLK)/2]-5$	
-60	MAX			8		t _C (H)×2 ^{32‡}		$ [t_{c}(TCLK)/2] - 5 [t_{c}(TCLK)/2] + 5 [t_{c}(TCLK)/2] - 5 [t_{c}(TCLK)/2] + 5$	
,C31-60	NIM	9	0		t _c (H)×2.6	t _c (H)×2	t _{c(H)} +10	$[t_{c}(TCLK)/2]-5$	
'C31-50	MAX			6		t _C (H)×2 ^{32‡}		$[t_c(TCLK)/2]+5$	
:C3.	MIN	8	0		t _C (H)×2.6	t _C (H)×2	t _{C(H)} +10	[tc(TCLK)/2]-5	
TINOITEIGUS		Setup time, TCLK external tsu(TCLK-H1L) before H1 low	Hold time, TCLK external after H1 low	Delay time, H1 high to TCLK internal valid	TCLK ext	TCLK int	TCLK ext	TCLK int	
		tsu(TCLK-H1L)	89 th(H1L-TCLK)	90 td(H1H-TCLK) internal valid	; ;	e (ICLK)	: : :	32 w(ICLK)	
Ç	<u>.</u>	88	88	06	5	5	6	36	

† Timing parameters 88 and 89 are applicable for a synchronous input clock. Timing parameters 91 and 92 are applicable for an asynchronous input clock. ‡ Specified by design but not tested



timer pin timing (continued)



NOTE A: HOLDA goes low in response to HOLD going low and continues to remain low until one H1 cycle after HOLD goes back high.

Figure 31. Timing for Timer Pin

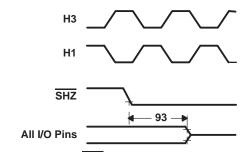
SHZ pin timing

The following table defines the timing parameter for the SHZ pin. The number shown in Figure 32 corresponds with that in the NO. column of the table below.

timing parameters for SHZ (see Figure 32)

NO.		'C3 'LC:		UNIT
		MIN	MAX	
93	t _{dis(SHZ)} Disable time, SHZ low to all O, I/O pins disabled (high impedance)	0†	2P†‡	ns

[†] This value is characterized but not tested



NOTE A: Enabling SHZ destroys TMS320C3x register and memory contents.

Assert SHZ = 1 and reset the TMS320C3x to restore it to a known condition.

Figure 32. Timing for SHZ



 $P = t_{C(CI)}$

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SHZ pin timing (continued)

Table 1. Thermal Resistance Characteristics

PARAMETER	°C/W	AIR FLOW LFPM
R _θ JC [†]	11.0	N/A
R ₀ JA [‡]	49.0	0
R _{θJA} ‡	35.5	200
R _{θJA} ‡	28.0	400
R _{θJA} ‡	23.5	600
R ₀ JA [‡]	21.6	800
R _{θJA} ‡	20.0	1 000

 $[\]dagger$ R_{OSC} = junction-to-case \ddagger R_{OJA} = junction-to-free air

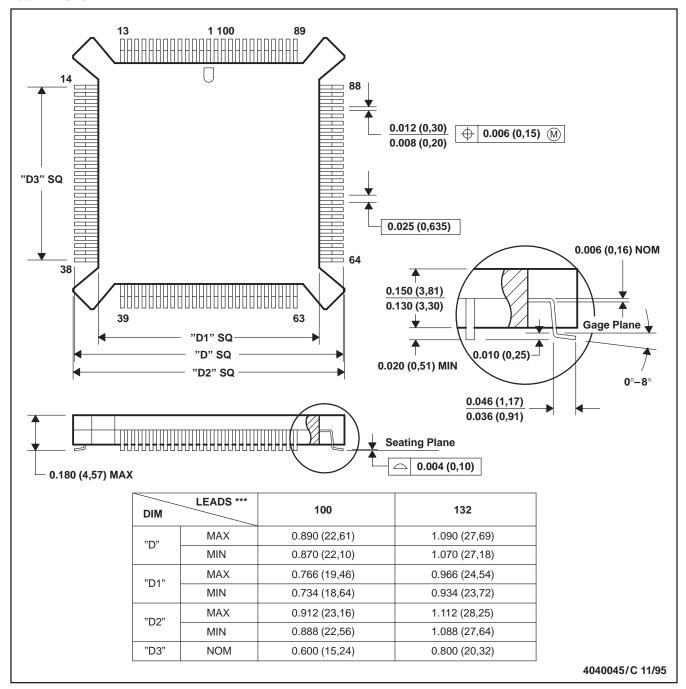
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MECHANICAL DATA

PQ (S-PQFP-G***)

100 LEAD SHOWN

PLASTIC QUAD FLATPACK



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MO-069



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